



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20130904000

**Aizu Facility as an additional FAB source for select devices in the F05 Process
Change Notification / Sample Request**

Date: 9/5/2013
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20130904000
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TMS320F28027PTT	null
TMS320F28027PTS	null
TMS320F28027FPTT	null
TMS320F28027DAT	null
TMS320F28027DAS	null
TMS320F28026PTS	null
TMS320F28026DAT	null
TMS320F28026DAS	null
TMS320F28023DAT	null
TMS320F28023DAS	null
TMS320F280230PTT	null
TMS320F28022PTT	null
TMS320F28021PTT	null
TMS320F28021DAS	null
TMS320F28020PTS	null
TMS320F28020DAT	null
TMS320F280200PTT	null
TMS320F280200DAT	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	PCN20130904000			PCN Date:	09/05/2013
Title:	Aizu Facility as an additional FAB source for select devices in the F05 Process				
Customer Contact:	PCN Manager		Phone:	+1(214)480-6037	Dept: Quality Services
Proposed 1st Ship Date:	12/05/2013		Estimated Sample Availability:	Date provided at sample request.	
Change Type:					
<input type="checkbox"/> Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials	
<input type="checkbox"/> Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification	
<input type="checkbox"/> Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	
<input type="checkbox"/> Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process	
<input checked="" type="checkbox"/> Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process	
	<input type="checkbox"/>	Part number change			

PCN Details

Description of Change:

This notification is to announce AIZU fabrication facility as an additional wafer FAB source for select devices in the F05 Process. The affected devices are listed in "Product Affected" section.

Currently Qualified Sites, Process, Wafer Dia.	Additional Site, Process, Wafer Dia.
DM5, F05 Process, 200mm	AIZU, F05 Process, 200mm

The F05 process was qualified in Aizu in June 2012. Qualification details are provided in the Qual Data Section.

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Current

Chip Site	Chip site code (20L)	Chip country code (21L)
DP1DM5	DM5	USA

Additional

Chip Site	Chip site code (20L)	Chip country code (21L)
AIZU	CU2	JPN

Sample product shipping label (not actual product label)



Product Affected:				
SM02028APTT	TMS320F28021PTT	TMS320F28023DAT	TMS320F280270DAT	
SM28020PTT	TMS320F280220DAS	TMS320F28023PTS	TMS320F280270PTS	
SM28021PTT	TMS320F280220DAT	TMS320F28023PTT	TMS320F280270PTT	
TJF026PTT	TMS320F280220PTS	TMS320F280260DAS	TMS320F28027DAS	
TMS320F280200DAS	TMS320F280220PTT	TMS320F280260DAT	TMS320F28027DASR	
TMS320F280200DAT	TMS320F28022DAS	TMS320F280260PTS	TMS320F28027DAT	
TMS320F280200PTS	TMS320F28022DAT	TMS320F280260PTT	TMS320F28027DATR	
TMS320F280200PTT	TMS320F28022PTS	TMS320F28026DAS	TMS320F28027FPTT	
TMS320F28020DAS	TMS320F28022PTSR	TMS320F28026DASR	TMS320F28027PTR	
TMS320F28020DAT	TMS320F28022PTT	TMS320F28026DAT	TMS320F28027PTS	
TMS320F28020PTS	TMS320F280230DAS	TMS320F28026DATR	TMS320F28027PTT	
TMS320F28020PTT	TMS320F280230DAT	TMS320F28026FPTT	TMS320F28KNWMX1	
TMS320F28021DAS	TMS320F280230PTS	TMS320F28026PTS	TMS320SPC0200PTT	
TMS320F28021DAT	TMS320F280230PTT	TMS320F28026PTT		
TMS320F28021PTS	TMS320F28023DAS	TMS320F280270DAS		

Qualification Data: Approved 8/30/2013														
This qualification has been developed for the validation of this change. The qualification data will validate that the proposed change meets the applicable released technical specifications.														
Qual Vehicle 1: TMS320F2802XAPT														
<table border="1"> <tr> <td>Wafer Fab Site:</td><td>AIZU</td><td>Metallization:</td><td colspan="2">TiN/AlCu/TiN</td></tr> <tr> <td>Wafer Fab Process:</td><td>F05</td><td>Wafer diameter:</td><td colspan="2">200mm</td></tr> </table>					Wafer Fab Site:	AIZU	Metallization:	TiN/AlCu/TiN		Wafer Fab Process:	F05	Wafer diameter:	200mm	
Wafer Fab Site:	AIZU	Metallization:	TiN/AlCu/TiN											
Wafer Fab Process:	F05	Wafer diameter:	200mm											
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results														
Reliability Test		Conditions		Sample Size/Fail										
				Lot#1 Lot#2 Lot#3										
Preconditioning	MSL2/260C			540/0 - -										
*Temp Cycle	-65C/150C 500 Cycles (actual 1000 cycles)			231/0 - -										
*Autoclave	121C/96hrs (actual 168 hours)			231/0 - -										
Notes:	* Test requires Moisture Preconditioning Qualification tests "pass" on zero fails for each test													
Qual Vehicle 2: TMS320F2802XADA														
<table border="1"> <tr> <td>Wafer Fab Site:</td><td>AIZU</td><td>Metallization:</td><td colspan="2">TiN/AlCu/TiN</td></tr> <tr> <td>Wafer Fab Process:</td><td>F05</td><td>Wafer diameter:</td><td colspan="2">200mm</td></tr> </table>					Wafer Fab Site:	AIZU	Metallization:	TiN/AlCu/TiN		Wafer Fab Process:	F05	Wafer diameter:	200mm	
Wafer Fab Site:	AIZU	Metallization:	TiN/AlCu/TiN											
Wafer Fab Process:	F05	Wafer diameter:	200mm											
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results														
Reliability Test		Conditions		Sample Size/Fail										
				Lot#1 Lot#2 Lot#3										
Preconditioning	MSL2/260C			720/0 - -										
*Temp Cycle	-65C/150C 500 Cycles(actual 750 cycles)			231/0 - -										
*Autoclave	121C/96hrs (actual 168 hours)			231/0 - -										
*High Temp Storage Life	150C, 500 hours			231/0 - -										
ESD-HBM	2000v			3/0 - -										
ESD-CDM	750v			3/0 - -										
Latchup	1.5Vdd +/-100mA 125C			6/0 - -										
Notes:	* Test requires Moisture Preconditioning Qualification tests "pass" on zero fails for each test													

Reference Qual: F05 Process Qualification at Aizu

Qualification Data: Approved 06/2012						
This qualification has been developed for the validation of this change. The qualification data will validate that the proposed change meets the applicable released technical specifications.						
Qual Vehicle 1: TMS320F2803XAPN						
Wafer Fab Site:	AIZU	Metallization:	TiN/AlCu/TiN			
Wafer Fab Process:	F05	Wafer diameter:	200mm			
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results						
Reliability Test	Conditions			Sample Size/Fail		
				Lot#1	Lot#2	Lot#3
20K W/E	20K Write / Erase Cycles prior to HTSL, HTOL, RTSL			1800/0	-	-
High Temperature Op Life	125C - 1000 Hours			231/0	-	-
*High Temp Storage Life	150C Bake - 1000 Hours			231/0	-	-
Room Temp Storage Life	25C - 1000 Hours			231/0	-	-
Package Reliability					-	-
*Preconditioning	MSL3/260C			693/0	-	-
*THB	85C/85RH			231/0	-	-
*Temp Cycle	-65C/150C 500 Cycles			231/0	-	-
*Autoclave	121C/96hrs			231/0	-	-
ESD-HBM	2000v			15/0	-	-
ESD-CDM	750v			6/0	-	-
Latch up	1.5Vdd +/-100mA 125C			6/0	-	-
Notes: * Test requires Moisture Preconditioning Qualification tests "pass" on zero fails for each test						

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com